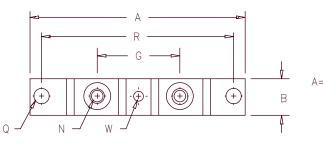
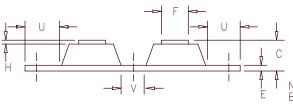
Schottky PowerMod

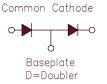












Baseplate: Nickel plated copper

Dim. Inches		Millimeters		
Min.	Max.	Min.	Max.	Notes
B 0.700 C E 0.120 F 0.490 G 1.375 H 0.010 N Q 0.275 R 3.150 U 0.600 V 0.312	0.510 BSC 0.290 BSC	12.45 34.92 0.25 6.99 80.0 15.24 7.92	7.37 BSC	1/4-28 Dia.

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	
CPT20130* CPT20135*	MBR20030CT 200CNQ035 224CNQ035 MBR20035CT	30V 35V	30V 35V
CPT20140*	200CNQ040 224CNQ040 MBR20040CT	40V	40V
CPT20145*	200CNQ045 224CNQ045 MBR20045CT	45V	45V
*Add Sut	fix A for Com	mon Anode, D fo	r Doubler

- Schottky Barrier Rectifier
- Guard Ring Protection
- 200 Amperes/30 to 45 Volts
- 150° C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

|F(AV) 200 Amps Average forward current per pkg Average forward current per leg F(AV) 100 Amps I FSM Maximum surge current per leg 2000 Amps Maximum repetitive reverse current per leg | R(OV) 2 Amps VFM 0.68 Volts Max peak forward voltage per leg V_{FM} Max peak forward voltage per leg 0.64 Volts ^IRM 1100mA Max peak reverse current per leg Max peak reverse current per leg ^IRM 4.0mA C_J 5500pF Typical junction capacitance

 ^{T}C = 99°C, Square wave, $^{R}\Theta JC$ = .20°C/W ^{T}C = 99°C, Square wave, $^{R}\Theta JC$ = .40°C/W 8.3ms, half sine, TJ = 125°C f = 1 KHZ, 25°C FM = 200A: TJ = 25°C* FM = 200A: TJ = 125°C* VRRM, TJ = 125°C* VRRM, TJ = 25°C*

 $VR = 5.0V, TC = 25^{\circ}C$

*Pulse test: Pulse width 300 usec, Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range Operating junction temp range Max thermal resistance per leg Typical thermal resistance (greased) Terminal Torque Mounting Base Torque (outside holes) Mounting Base Torque (center hole) center hole must be torqued first Weight

TSTG -55°C to 150°C ΤJ -55°C to 150°C 0.40°C/W Junction to case R OJC Recs

0.08°C/W Case to sink 35-40 inch pounds 30-40 inch pounds 8-10 inch pounds

2.8 ounces (75 grams) typical



CPT20130 - CPT20145

Figure 1 Maximum Forward Characteristics — Per Lea

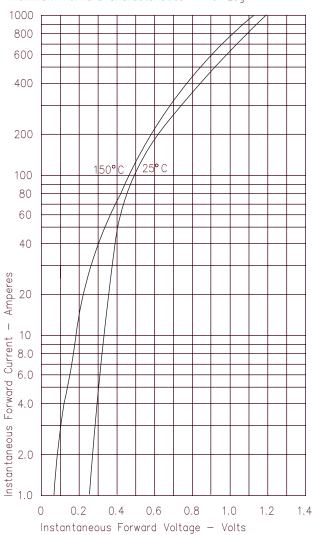


Figure 3
Typical Junction Capacitance — Per Leg

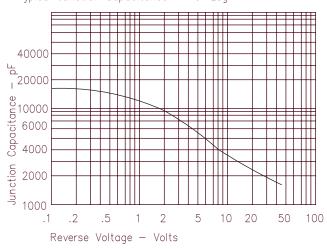


Figure 4 Forward Current Derating — Per Leg

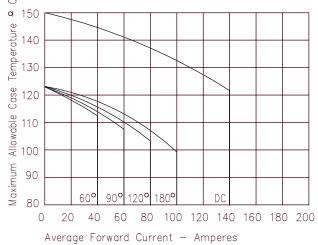


Figure 2 Typical Reverse Characteristics — Per Leg

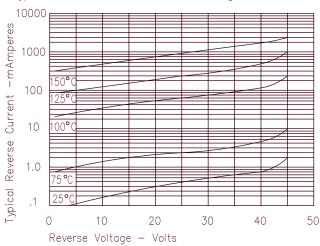
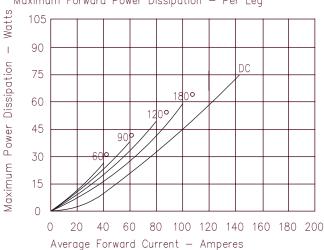


Figure 5
Maximum Forward Power Dissipation — Per Leg





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